

Title (en)
METHOD OF SINTERING ELECTRICALLY CONDUCTING POWDERS

Title (de)
VERFAHREN ZUM SINTERN VON ELEKTRISCH LEITFÄHIGEN PULVERN

Title (fr)
PROCÉDÉ DE FRITTAGE DE POUDRES ÉLECTRIQUEMENT CONDUCTRICES

Publication
EP 3208015 B1 20190501 (EN)

Application
EP 16382069 A 20160219

Priority
EP 16382069 A 20160219

Abstract (en)
[origin: EP3208015A1] The method comprises placing the powders in an electrically isolating mold, applying a pressure to the powders between 100 and 500MPa and applying to the powders a sintering current at a sintering voltage during a sintering time, for sintering the powders. Before applying the sintering current density, applying an activation current density lower than the sintering current density at an activation voltage greater than the sintering voltage during an activation time lower than the sintering time, to reduce the electrical resistance of the powders.

IPC 8 full level
B22F 3/087 (2006.01); **B01J 19/08** (2006.01); **B22F 3/105** (2006.01); **B30B 11/00** (2006.01); **B22F 3/16** (2006.01); **C22C 14/00** (2006.01); **C22C 21/00** (2006.01); **C22C 29/08** (2006.01); **C22C 29/10** (2006.01); **C22C 32/00** (2006.01)

CPC (source: CN EP US)
B22F 3/003 (2013.01 - CN); **B22F 3/087** (2013.01 - EP US); **B22F 3/105** (2013.01 - CN EP US); **B22F 3/14** (2013.01 - CN); **B22F 3/164** (2013.01 - EP US); **B22F 2003/1051** (2013.01 - EP US); **B22F 2201/50** (2013.01 - EP US); **B22F 2202/06** (2013.01 - EP US); **B22F 2301/15** (2013.01 - EP US); **B22F 2301/205** (2013.01 - EP US); **B22F 2301/40** (2013.01 - EP US); **B22F 2998/10** (2013.01 - EP US); **C22C 14/00** (2013.01 - EP US); **C22C 21/00** (2013.01 - EP US); **C22C 29/08** (2013.01 - US); **C22C 29/10** (2013.01 - US); **C22C 32/0052** (2013.01 - US)

Cited by
EP3702065A1; CN111748717A

Designated contracting state (EPC)
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DOCDB simple family (publication)
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EP 16382069 A 20160219; CN 201710089756 A 20170220; DK 16382069 T 20160219; ES 16382069 T 20160219; US 201715436844 A 20170219